PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jovica Savic	11/08/2011
Zhiping Yang	11/11/2011
Jie Xue	11/08/2011
Li Li	11/15/2011

RECEIVING PARTY DATA

Name:	Cisco Technology, Inc.
Street Address:	170 West Tasman Drive
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95134-1706

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	13296707	

CORRESPONDENCE DATA

 Fax Number:
 (301)762-4056

 Phone:
 301-424-3640

 Email:
 alc@usiplaw.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: Edell, Shapiro & Finnan, LLC Address Line 1: 1901 Research Boulevard

Address Line 2: Suite 400

Address Line 4: Rockville, MARYLAND 20850

ATTORNEY DOCKET NUMBER: 13/296,707 (0370.1132C)

NAME OF SUBMITTER: Andrew J. Aldag

PATENT

REEL: 027233 FRAME: 0724

OP \$40.00 13296/0/

Total Attachments: 4

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> PATENT REEL: 027233 FRAME: 0725

For good and valuable consideration, WE, Jovica Savic, having a mailing address at 170 West Tasman Drive, San Jose, CA 95134; Zhiping Yang, having a mailing address at 20625 Wildflower Way, Cupertino, CA 95014; Jie Xue, having a mailing address at 3215 Spicewood Lane, San Ramon, CA 94582; and Li Li, having a mailing address at 170 West Tasman Drive, San Jose, CA 95134; hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Cisco Technology, Inc., a corporation organized and existing under the laws of California, having its principal place of business at 170 West Tasman Drive, San Jose, California 95134-1706, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

entitled: MANUFACTURING A SEMICONDUCTOR PACKAGE INCLUDING AN EMBEDDED CIRCUIT COMPONENT WITHIN A SUPPORT STRUCTURE OF THE PACKAGE

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed

by the undersign	M S. L	DATE 1/8/201/
SIGNATURE: {	Apvica Savic	DATE:
SIGNATURE: $^{\ell}$		DATE:
	Zhiping Yang	
SIGNATURE:		DATE:
	Jie Xue	
SIGNATURE:		DATE:
	Li Li	

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SIGNATURE:		DATE:	
	Jovica Savic		
SIGNATURE:		DATE:	11/11/2011
	Zhiping Yang		, ,
SIGNATURE:		DATE:	(NO. 10. 10. 10. 10. 10. 10. 10. 10. 10. 10
	Jie Xue		
SIGNATURE:		DATE:	***************************************
	LiLi		

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SIGNATURE:		DATE	
	Zhiping Yang		
SIGNATURE:		DATE:	
	Jie Xue		11/15/2011
SIGNATURE:		DATE:	11/13/2011
	LiLi		

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RECORDED: 11/16/2011